



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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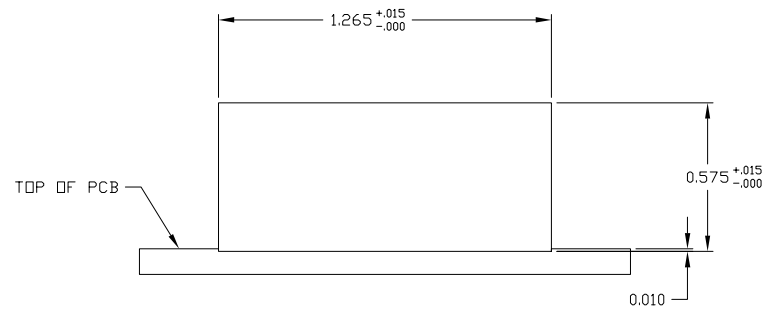
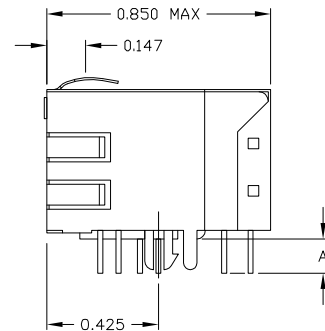
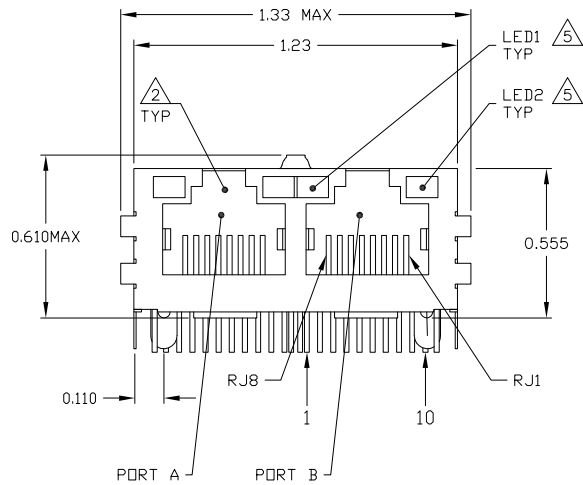
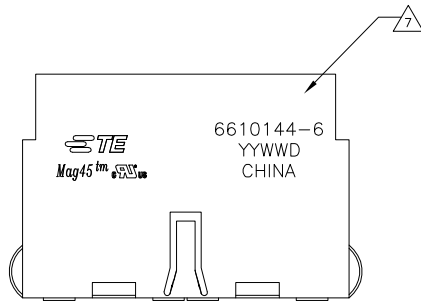
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LOC	DATE	REVISIONS	DATE	BY	APP'D
AA	22				
D	REV PER ECO-08-015464		05JUN2008	QL	TX
E	ECO-11-013425		20MAY2011	EL	LR

MECHANICAL:



1X2 SUGGESTED PANEL CUTOUT

- 1 MATERIALS:
 -HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
 -SHIELD - 0.010" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
 -MOD JACK CONTACTS - 0.0157" X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE.
 SOLDERTAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 -LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, 0.020" X 0.020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.

- 2 RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.

- 3 MAGNETICS
 -IMPEDANCE: 100 OHMS
 -TURNS RATIO (CHIP: CABLE): 1:1 ALL FOUR PAIRS
 -OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0 °C TO 70 °C, ALL FOUR PAIRS
 -ALL FOUR PAIRS BI-DIRECTIONAL
 -PERFORMANCE @ 25 °C:
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 40MHz
 12-20LOG(f/80)dB MIN FROM 40.1MHz TO 100MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 33-20xLOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 -ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC AND WITH ALL PORTS CONNECTED.

4. OPERATING TEMPERATURE: FROM 0°C TO + 70°C.

- 5 LED IS DRIVEN WITH CONSTANT CURRENT AT APPROX 20mA.
 LED COLOR:DOMINANT WAVELENGTH(D):GREEN 568nm TYP. AT IF=20mA
 FORWARD VOLTAGE (VF): GREEN 2.2V TYP. AT IF=20mA
 DOMINANT WAVELENGTH(D):YELLOW 588nm TYP. AT IF=20mA
 FORWARD VOLTAGE (VF): YELLOW 2.1V TYP. AT IF=20mA.

- 6 THE MAGNETICS ARE SYMMETRICAL AND SUPPORT AUTO-MDI/MDIX.

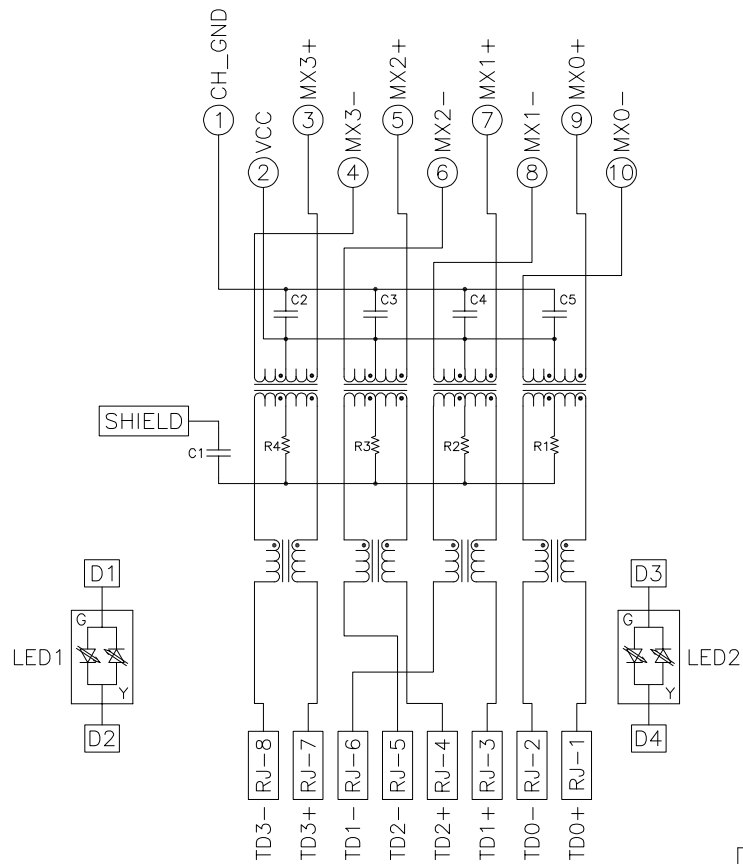
- 7 TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.

8. THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS, PEAK WAVE SOLDERING TEMPERATURE IS 265°C MAX, 10 SECONDS MAX.

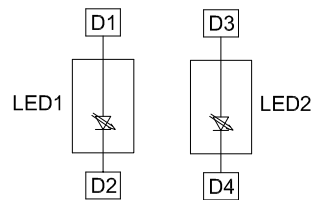
0.110±0.010	GREEN/YELLOW	GREEN/YELLOW	2-6610144-6
0.145±0.010	GREEN	YELLOW	6610144-8
0.145±0.010	GREEN/YELLOW	GREEN/YELLOW	6610144-6
DIM "A"	LED1	LED2	PART NUMBER

DIMENSIONS:		DRAWING NO.		REV	
0 P/C	± -	100779	1	2	F
1 P/C	± .010				
2 P/C	± .005				
3 P/C	± .008				
4 P/C	± .008				
ANGLES	± .4				
MATERIAL	FINISH	WEIGHT	SCALE	SHEET	REV
			4:1	1 of 2	

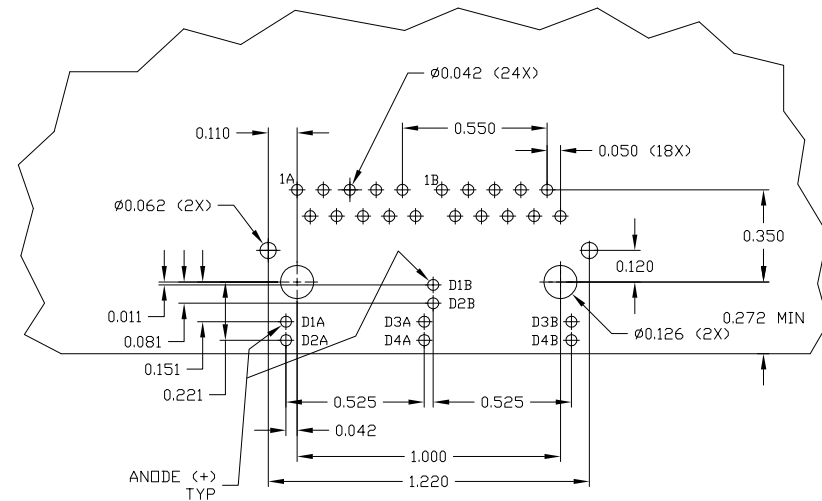
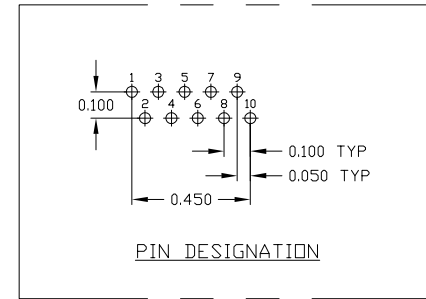
7G06 SERIES GIGABIT CIRCUIT ³/₆



C1 = 1000pF, 2kV CAPACITOR.
 R1-R4 = 75 OHMS, 1/16W RESISTORS.
 C2-C5 = 0.1µF, 50V, X7R CAPACITORS.

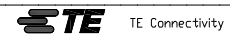


LED CONFIGURATION
 6610144-8 ONLY



SUGGESTED PCB LAYOUT
 (Component Side)

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV	A	DATE	18MAR2008	NAME	A. FERNANDEZ-RODRIGUEZ
DRAWN BY: D. FAROLE		CHKD	D. FAROLE	DATE	18MAR2008	NAME	D. FAROLE
DIMENSIONS:		INCHES					
0 P.C.	± .005	1 P.C.	± .010	2 P.C.	± .015	3 P.C.	± .020
4 P.C.	± .025	ANGLES	± .005				
MATERIAL		FINISH		WEIGHT		SIZE	A1
						DATE CODE	00779
						DRAWING NO	C=6610144
						RESTRICTED TO	
						SCALE	1:1
						SHEET	2 of 2
						REV	F



1X2 MAG45(TW) MODULAR JACK, 704 SCHEMATIC,
 (10 PIN HORIZONTAL), 7G06 SERIES GIGABIT CIRCUIT,
 SHIELDED, WITH LEADS